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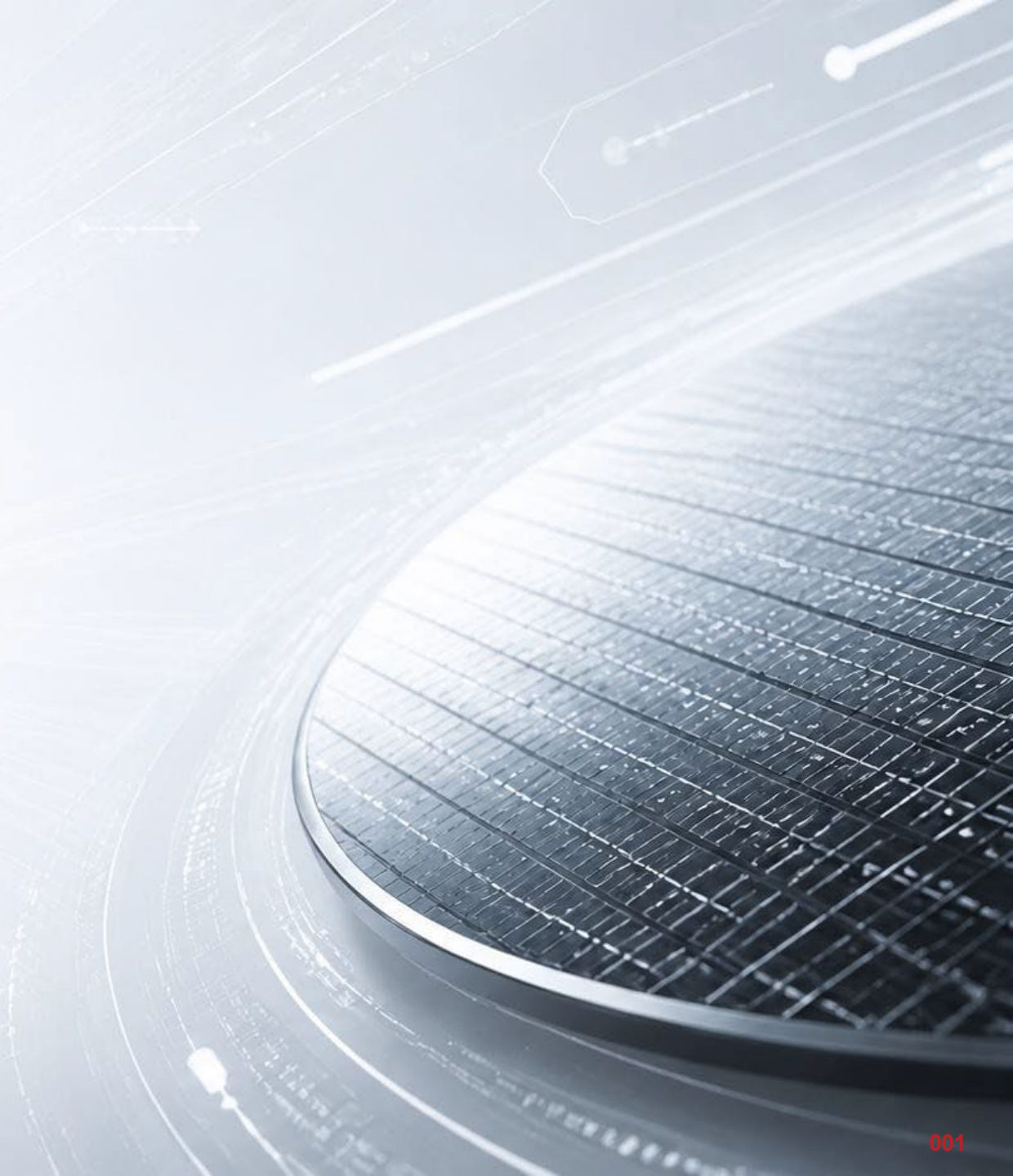
MARKET RESEARCH REPORT

KAYOU

SiC Industry Report

H1 2026

Global Trends and Structural Shifts
in China's SiC Market



KAYOU Co., Ltd.

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Highlights · Research Overview · Global Developments · China's SiC Industry

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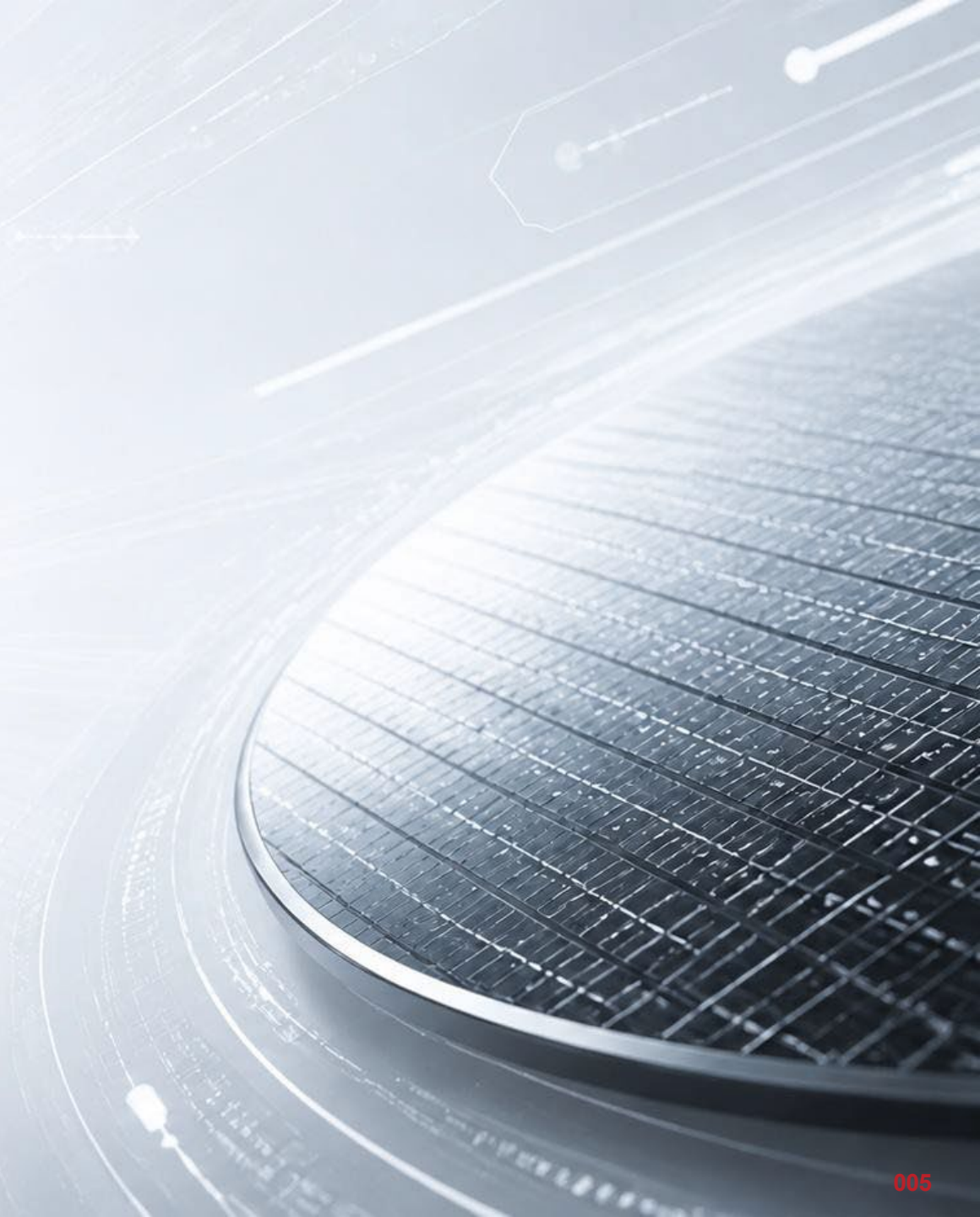
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KEY TOPICS

KAYOU SiC Industry Report

H1 2026



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10 Major Developments Shaping the SiC Industry in H1 2026

Verified milestones across materials, production, devices and end markets

01
03.27

Toshiba, ROHM and Mitsubishi Electric in integration talks

The firms signed an MoU covering semiconductors and power devices; integration terms remain undecided.

02
Q2

ST starts 200 mm SiC production in Italy and China

Production began in Catania and Chongqing. A July disclosure confirmed the H1 start.

03
May

Bosch shifts German SiC output to 200 mm

Bosch ended 150 mm SiC production in Reutlingen and completed its transition to 200 mm.

04
01.13

Wolfspeed announces 300 mm single-crystal SiC

Wolfspeed reported successful wafer fabrication, not commercial mass production.

05
Mar

ROHM develops fifth-generation SiC MOSFETs

Developed in March and announced in April, with about 30% lower on-resistance at 175°C.

06
04.28

Geely and onsemi expand 900 V EV collaboration

The partners announced plans to integrate EliteSiC into an SEP system based on SEA-S.

07
03.24

Infineon partners on SiC solid-state transformers

Infineon will supply SiC for DG Matrix's Interport, targeting AI power infrastructure.

08
03.05

Wolfspeed commercializes 10 kV SiC devices

The announced 10 kV power MOSFETs target medium-voltage supplies and SST systems.

09
03.30

Epiworld earmarks IPO proceeds for epi capacity

Net proceeds were about HK$1.56 billion, with 71% planned for epi-capacity expansion.

10
01.16

TYSiC and Qinghe to develop bonded SiC substrates

Cooperation covers 8-inch bonded SiC and composite heat-spreading substrates of 12 inches or more.

Period: Jan–Jun 2026 | Information verified: 2026.10.30 | Editorial selection by KAYOU; not ranked. Figures and plans are based on company disclosures.

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Contact Us

China SiC market insights, sourcing and business partnerships

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